

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): An electrosurgical device including an electrode, a handle connected to the electrode and an electrical source in communication with the handle to transfer electrical energy to the electrode for contacting tissue in a body during an electrosurgical procedure, said electrode comprising:

a conductive substrate; and

at least one substantially uniform coating applied to said substrate, wherein the coating includes a base material and a plurality of anti-microbial particles interspersed in said base material, wherein said anti-microbial particles are formulated to reduce or kill a plurality of microbial organisms independent of any energy source.

Claim 2 (original): The electrosurgical device of Claim 1, wherein the conductive substrate includes a metal.

Claim 3 (original): The electrosurgical device of Claim 2, wherein the metal includes stainless steel.

Claim 4 (original): The electrosurgical device of Claim 1, wherein at least a portion of the conductive substrate includes an electrically insulative material, which is applied to the surface of the conductive substrate.

Claim 5 (original): The electrosurgical device of Claim 4, wherein only a portion of the conductive substrate underneath the insulative material includes the substantially uniform coating.

Claim 6 (original): The electrosurgical device of Claim 1, wherein the base material includes a non-stick material.

Claim 7 (original): The electrosurgical device of Claim 6, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 8 (original): The electrosurgical device of Claim 1, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 9 (withdrawn): An electrosurgical device including an electrode, a handle connected to the electrode and an electrical source in communication with the handle to transfer electrical energy to the electrode for contacting tissue in a body during an electrosurgical procedure, said electrode comprising:

- a conductive substrate;
- a wet bonding material applied to the surface of the substrate;
- a single layer of substantially uniform anti-microbial particles applied to the wet bonding material; and
- a top coating applied to the layer of anti-microbial particles.

Claim 10 (withdrawn): The electrosurgical device of Claim 9, wherein the conductive substrate includes a metal.

Claim 11 (withdrawn): The electrosurgical device of Claim 10, wherein the metal includes stainless steel.

Claim 12 (withdrawn): The electrosurgical device of Claim 9, wherein the wet bonding material includes a primer.

Claim 13 (withdrawn): The electrosurgical device of Claim 9, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 14 (withdrawn): The electrosurgical device of Claim 9, wherein the top coating includes a non-stick material.

Claim 15 (withdrawn): The electrosurgical device of Claim 14, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 16 (withdrawn): The electrosurgical device of Claim 9, wherein the top coating includes at least one of the following powdered coatings: polytetrafluoroethylene, perfluoroalkoxy, MFA and fluorinated ethylene propylene.

Claim 17 (original): The electrosurgical device of Claim 1, wherein at least a portion of the conductive substrate includes an electrically insulative material, which is applied to the surface of the conductive substrate.

Claim 18 (currently amended): The electrosurgical device of Claim 17, wherein only a portion of the conductive substrate underneath the insulative material includes the a top coating.

Claim 19 (withdrawn): An electrosurgical instrument comprising:

- a conductive substrate including a proximal end and a distal end;
- a handle connected to the proximal end of said substrate;
- at least one electrical transfer member connected to the handle, which transfers electrical energy from an electrical source through the handle to the conductive substrate; and
- a wet bonding material applied to the surface of the substrate;
- a single layer of substantially uniform anti-microbial particles applied to the wet bonding material; and
- a top coating applied to the layer of anti-microbial particles.

Claim 20 (withdrawn): The electrosurgical device of Claim 19, wherein the conductive substrate includes a metal.

Claim 21 (withdrawn): The electrosurgical device of Claim 20, wherein the metal includes stainless steel.

Claim 22 (withdrawn): The electrosurgical device of Claim 19, wherein the top coating includes a non-stick material.

Claim 23 (withdrawn): The electrosurgical device of Claim 22, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 24 (withdrawn): The electrosurgical device of Claim 19, wherein the top coating includes at least one of the following powdered coatings: polytetrafluoroethylene, perfluoroalkoxy, MFA and fluorinated ethylene propylene.

Claim 25 (withdrawn): The electrosurgical device of Claim 19, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 26 (withdrawn): The electrosurgical device of Claim 19, wherein at least a portion of the conductive substrate includes an electrically insulative material, which is applied to the surface of the conductive substrate.

Claim 27 (withdrawn): The electrosurgical device of Claim 26, wherein only a portion of the conductive substrate underneath the insulative material includes the top coating.

Claim 28 (currently amended): An electrosurgical instrument comprising:
a conductive substrate including a proximal end and a distal end;
a handle connected to the proximal end of said substrate;
at least one electrical transfer member connected to the handle, which transfers electrical energy from an electrical source through the handle to the conductive substrate; and
at least one substantially uniform coating applied to said substrate, wherein the coating includes a base material and a plurality of anti-microbial particles interspersed in said base material, wherein said anti-microbial particles are formulated to reduce or kill a plurality of microbial organisms independent of any energy source.

Claim 29 (withdrawn): The electrosurgical device of Claim 28, wherein the conductive substrate includes a metal.

Claim 30 (withdrawn): The electrosurgical device of Claim 29, wherein the metal includes stainless steel.

Claim 31 (withdrawn): The electrosurgical device of Claim 28, wherein the wet bonding material includes a primer.

Claim 32 (withdrawn): The electrosurgical device of Claim 28, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 33 (withdrawn): The electrosurgical device of Claim 28, which includes at least one top coating applied to the anti-microbial particles.

Claim 34 (withdrawn): The electrosurgical device of Claim 33, wherein the top coating includes a non-stick material.

Claim 35 (withdrawn): The electrosurgical device of Claim 34, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics, polytetrafluoroethylene, perfluoroalkoxy, MFA, fluorinated ethylene propylene and a combination of fluorosilicones.

Claim 36 (withdrawn): The electrosurgical device of Claim 33, wherein the top coating includes at least one of the following powdered coatings: polytetrafluoroethylene, perfluoroalkoxy, MFA and fluorinated ethylene propylene.

Claim 37 (withdrawn): The electrosurgical device of Claim 28, wherein at least a portion of the conductive substrate includes an electrically insulative material, which is applied to the surface of the conductive substrate.

Claim 38 (withdrawn): The electrosurgical device of Claim 37, wherein only a portion of the conductive substrate underneath the insulative material includes the top coating.

Claim 39 (currently amended): A method of coating an electrosurgical device including a conductive substrate, said method comprising the steps of:

(a) evenly applying a substantially uniform coating to a surface of the conductive substrate, said coating including a base material and a plurality of anti-microbial particles interspersed in the base material, wherein said anti-microbial particles are formulated to reduce or kill a plurality of microbial organisms independent of any energy source; and

(b) at least partially curing the substantially uniform coating.

Claim 40 (withdrawn): The method of Claim 39, which includes the step of applying wet bonding material to the surface of the conductive substrate prior to step (a).

Claim 41 (withdrawn): The method of Claim 40, wherein the wet bonding material includes a primer.

Claim 42 (withdrawn): The method of Claim 39, which includes the step of applying at least one additional coating to the surface of the substrate after step (a).

Claim 43 (withdrawn): The method of Claim 42, wherein the additional coating includes a non-stick material.

Claim 44 (withdrawn): The method of Claim 43, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 45 (withdrawn): The method of Claim 42, wherein the additional coating includes the base material and the plurality of anti-microbial particles interspersed in the base material.

Claim 46 (withdrawn): The method of Claim 39, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 47 (withdrawn): The method of Claim 39, wherein the base material includes a non-stick material.

Claim 48 (withdrawn): The method of Claim 47, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 49 (withdrawn): The method of Claim 39, which includes the step of applying a top coating to the substantially uniform coating, wherein the top coating includes at least one of the following powdered coatings: polytetrafluoroethylene, perfluoroalkoxy, MFA and fluorinated ethylene propylene or a mixture of these powdered coatings.

Claim 50 (withdrawn): The method of Claim 49, wherein the step of applying the top coating further includes the steps of:

- (a) placing the conductive substrate on a grounded support; and
- (b) electrostatically attracting the top coating to the substantially uniform coating.

Claim 51 (withdrawn): The method of Claim 39, which includes the step of applying an electrically insulative material to at least a portion of the surface of the conductive substrate.

Claim 52 (withdrawn): The method of Claim 51, wherein the step of applying the substantially uniform coating to the surface of the conductive substrate further includes applying the substantially uniform coating to only a portion of the surface of the conductive substrate underneath the insulative material.

Claim 53 (withdrawn): A method of coating an electrosurgical device including a conductive substrate, said method comprising the steps of:

- (a) applying a wet bonding material to at least a portion of a surface of the conductive substrate;
- (b) evenly applying a single layer of substantially uniform anti-microbial particles to the wet bonding material;
- (c) at least partially curing the wet bonding material and the substantially uniform anti-microbial particles; and
- (d) applying a top coating to the bonding material and the anti-microbial particles.

Claim 54 (withdrawn): The method of Claim 53, wherein the wet bonding material includes a primer.

Claim 55 (withdrawn): The method of Claim 53, which includes the step of repeating steps (a) to (c) until a desired thickness is achieved.

Claim 56 (withdrawn): The method of Claim 53, wherein the step of applying a top coating includes applying a non-stick material to the bonding material and the anti-microbial particles.

Claim 57 (withdrawn): The method of Claim 56, wherein the non-stick material includes at least one of the non-stick materials selected from the group consisting of: silicone, polytetrafluoroethylene, a fluoropolymer, ceramics and a combination of fluorosilicones.

Claim 58 (withdrawn): The method of Claim 53, wherein the anti-microbial particles include at least one of the group consisting of: silver particles and ceramic particles.

Claim 59 (withdrawn): The method of Claim 53, wherein the step of applying the top coating includes partially applying the top coating to the bonding material and the anti-microbial particles such that a portion of the anti-microbial particles are exposed at the surface of the conductive substrate.

Claim 60 (withdrawn): The method of Claim 53, which includes the step of removing at least a portion of the top coating to expose a portion of the anti-microbial particles at the surface of the conductive substrate.

Claim 61 (withdrawn): The method of Claim 60, wherein the step of removing the top coating includes sanding the top coating.

Claim 62 (withdrawn): The method of Claim 60, wherein the step of removing the top coating includes buffing the top coating.

Claim 63 (withdrawn): The method of Claim 53, wherein the step of applying a single layer of substantially uniform anti-microbial particles to the wet bonding material includes applying powdered anti-microbial particles.

Claim 64 (withdrawn): The method of Claim 53, wherein the step of applying the top coating further includes applying at least one of the following powdered coatings: polytetrafluoroethylene, perfluoroalkoxy, MFA and fluorinated ethylene propylene or a mixture of these powdered coatings.

Claim 65 (withdrawn): The method of Claim 64, wherein the step of applying the top coating further includes the steps of:

- (a) placing the conductive substrate on a grounded support; and
- (b) electrostatically attracting the top coating to the substantially uniform coating.

Claim 66 (withdrawn): The method of Claim 53, which includes the step of applying an electrically insulative material to at least a portion of the surface of the conductive substrate.

Claim 67 (withdrawn): The method of Claim 66, wherein the step of applying the top coating further includes applying the top coating to only a portion of the surface of the conductive substrate underneath the insulative material.